

# UTC UNISONIC TECHNOLOGIES CO., LTD

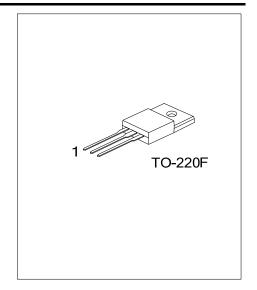
9N50 **Preliminary Power MOSFET** 

# **N-CHANNEL** 9A, 500V **POWER MOSFET**

#### **DESCRIPTION**

The UTC 9N50 is an N-channel mode power MOSFET using UTC's advanced technology to provide customers planar stripe and DMOS technology. This technology allows a minimum on-state resistance, superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

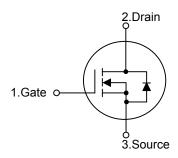
The UTC 9N50 is generally applied in high efficiency switch mode power supplies, active power factor correction and electronic lamp ballasts based on half bridge topology.



#### **FEATURES**

- \*  $R_{DS(ON)}$ =0.85 $\Omega$  @  $V_{GS}$ =10V
- \* High Switching Speed
- \* Improved dv/dt Capability
- \* 100% Avalanche Tested

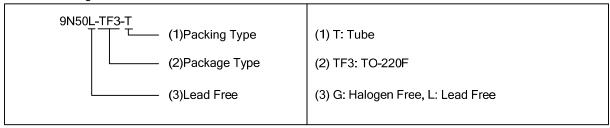
#### **SYMBOL**



#### **ORDERING INFORMATION**

Ordering Number		Dookone	Pin Assignment			Dealine	
Lead Free	Halogen Free	Package	1	2	3	Packing	
9N50L-TF3-T	9N50G-TF3-T	TO-220F	G	D	S	Tube	

Note: Pin Assignment: G: Gate D: Drain S: Source



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## ■ **ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub>=25°C, unless otherwise noted)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	500	V
Gate-Source Voltage		$V_{GSS}$	±30	V
Drain Current	Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	9 (Note 5)	Α
	Pulsed (Note 2)	I <sub>DM</sub>	36 (Note 5)	Α
Avalanche Current (Note 2)		I <sub>AR</sub>	9	Α
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	360	mJ
	Repetitive (Note 4)	E <sub>AR</sub>	13.5	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation		В	44	W
Derate above 25°C		- P <sub>D</sub>	0.35	W/°C
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55~+150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature
- 3. L = 8mH,  $I_{AS}$  = 9A,  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25 $^{\circ}$ C
- 4.  $I_{SD} \le 9A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$
- 5. Drain current limited by maximum junction temperature

#### **■ THERMAL DATA**

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	$\theta_{JA}$	62.5	°C/W	
Junction to Case	$\theta_{JC}$	2.86	°C/W	

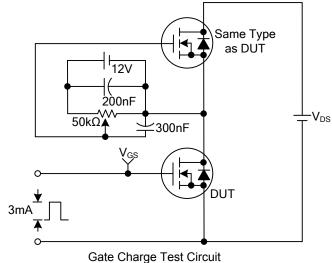
# ■ **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub>=25°C, unless otherwise noted)

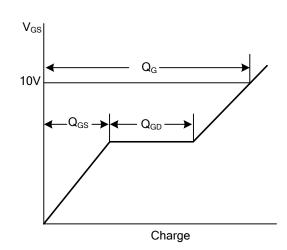
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS				L			
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V				V
Drain-Source Leakage Current			V <sub>DS</sub> =500V, V <sub>GS</sub> =0V			1	
		I <sub>DSS</sub>	V <sub>DS</sub> =400V, T <sub>C</sub> =125°C			10	μA
Gate- Source Leakage Current	orward		$V_{GS}$ =+30V, $V_{DS}$ =0V			+100	nA
	Reverse	$I_{GSS}$	$V_{GS}$ =-30V, $V_{DS}$ =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	$V_{GS}$ =10V, $I_D$ =4.5A		0.7	0.85	Ω
DYNAMIC PARAMETERS							
Input Capacitance	C <sub>ISS</sub>				790	1030	pF
Output Capacitance		Coss	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz		130	170	pF
Reverse Transfer Capacitance		$C_{RSS}$			24	30	pF
SWITCHING PARAMETERS							
Total Gate Charge		$Q_G$	V <sub>GS</sub> =10V, V <sub>DS</sub> =400V, I <sub>D</sub> =9A		28	35	nC
Gate to Source Charge		$Q_GS$	(Note 1, 2)		4		nC
Gate to Drain Charge		$Q_GD$			15		nC
Turn-ON Delay Time		$t_{D(ON)}$	$V_{DD}$ =250V, $I_{D}$ =9A, $R_{G}$ =25 $\Omega$ (Note 1, 2)		18	45	ns
Rise Time		$t_R$			65	140	ns
Turn-OFF Delay Time		t <sub>D(OFF)</sub>			93	195	ns
Fall-Time		$t_{F}$			64	125	ns
SOURCE- DRAIN DIODE RATING	GS AND (	CHARACTERI	STICS				
Maximum Body-Diode Continuous Current		Is				9	Α
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				36	Α
Drain-Source Diode Forward Voltage		$V_{SD}$	I <sub>S</sub> =9A, V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time		t <sub>rr</sub>	$I_S$ =9A, $V_{GS}$ =0V, $dI_F/dt$ =100A/ $\mu$ s				ns
Body Diode Reverse Recovery Charge		$Q_{RR}$	(Note 1)		2.95		μC

Notes: 1. Pulse Test: Pulse width  $\leq 300 \mu s$ , Duty cycle  $\leq 2\%$ 

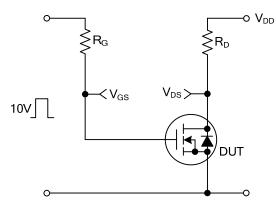
<sup>2.</sup> Essentially independent of operating temperature

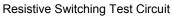
## **■ TEST CIRCUITS AND WAVEFORMS**

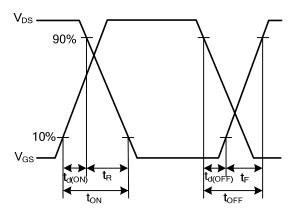




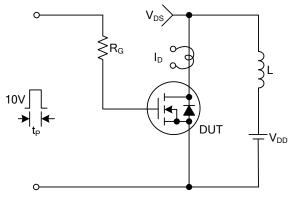
Circuit Gate Charge Waveforms



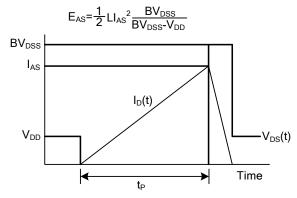




Resistive Switching Waveforms

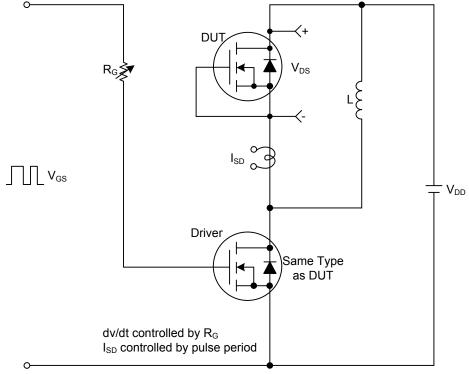


Unclamped Inductive Switching Test Circuit

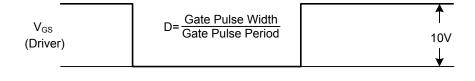


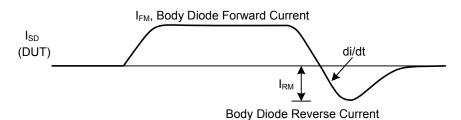
Unclamped Inductive Switching Waveforms

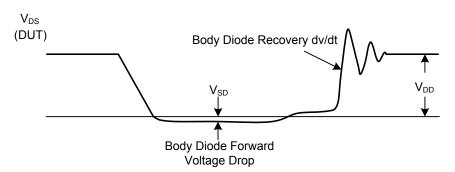
# ■ TEST CIRCUITS AND WAVEFORMS(Cont.)



Peak Diode Recovery dv/dt Test Circuit & Waveforms







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